

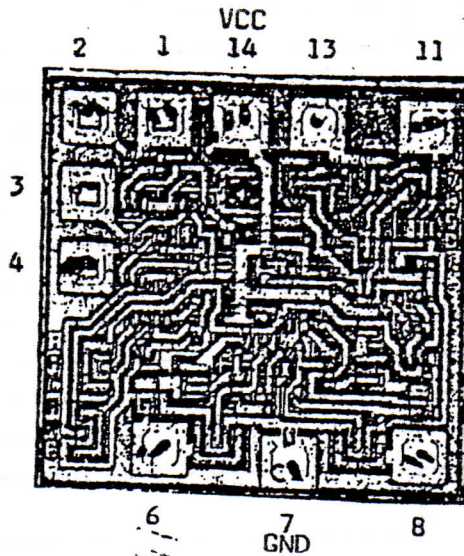


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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

<u>PAD</u>	<u>FUNCTION</u>
1	A1
2	A2
3	B1
4	B2
5	NC
6	\bar{Q}
7	GND
8	Q
9	NC
10	NC
11	CAP
12	NC
13	RX
14	VCC



Top Material: Aluminum
Backside Material: Silicon
Bond Pad Size: .004" X .004" min.
Backside Potential:
Mask Ref:

APPROVED BY: DK

DIE SIZE .041 X .041"

DATE: 5/16/16

MFG: National Semi.

THICKNESS .012"

P/N: 9601